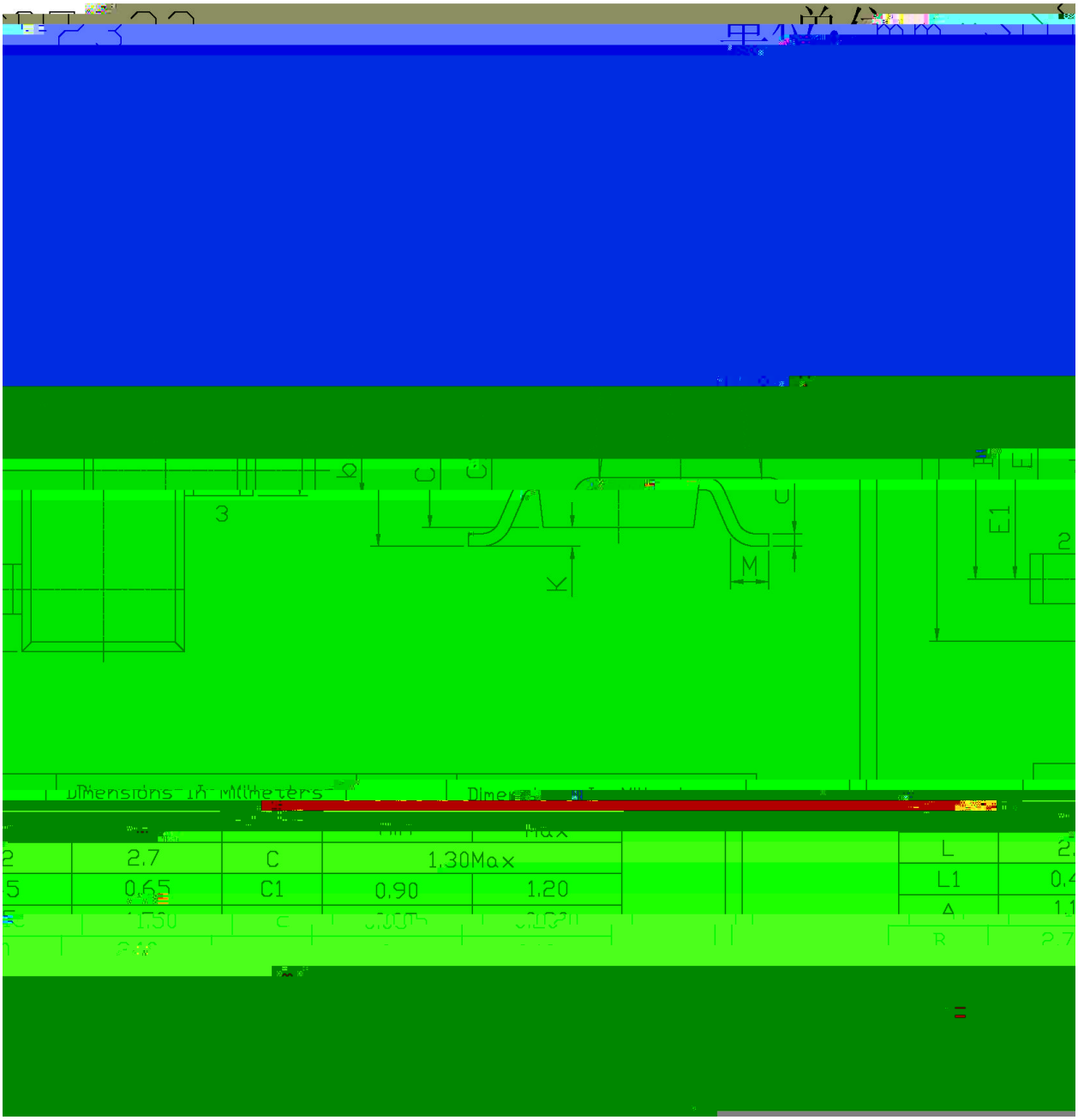
VRW-56 SQS

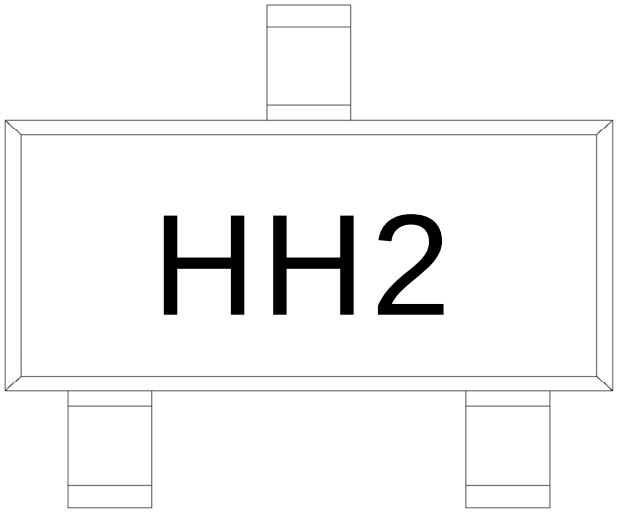
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-50	V
Collector to Emitter Voltage	V_{CEO}	-45	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current(DC)	I_C	-100	mA
Peak Collector Current	I_{CM}	-200	mA
Peak Base Current	I_{BM}	-200	mA
Collector Power Dissipation	P_C	250	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=-100μA I_E=0	-50			V
Collector to Emitter Breakdown Voltage	V_{CEO}	I_C=-500μA I_B=0	-45			V
Emitter to Base Breakdown Voltage	V_{EBO}	I_E=-100μA I_C=0	-5.0			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=-20 V I_E=0			-0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	V_{EB}=-5.0V I_C=0			-0.1	μA
	$h_{FE(1)}$	V_{CE}=-5.0V I_C=-2.0mA	215		500	

/ Package Dimensions



/ Marking Instructions



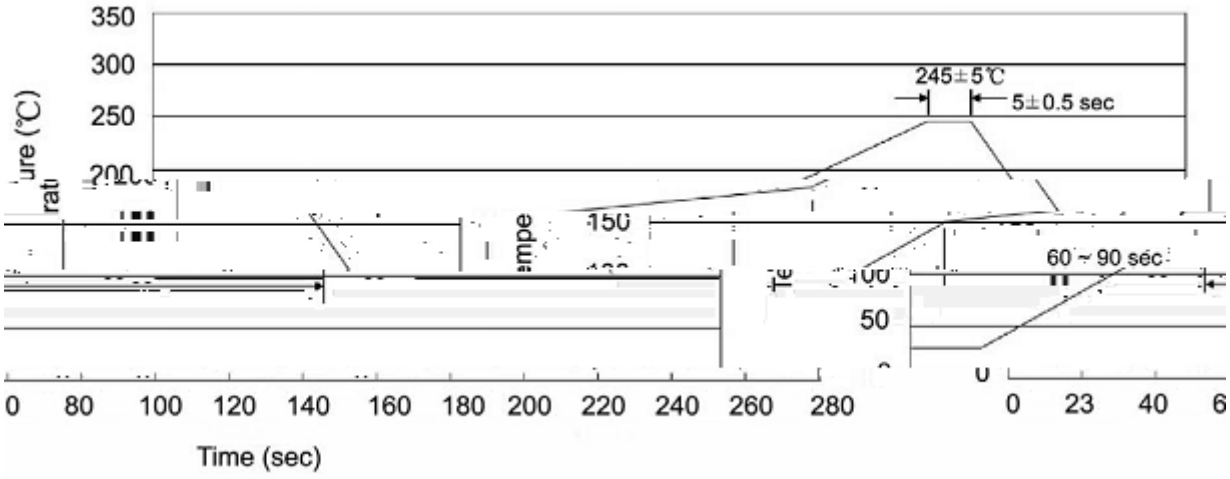
H	И
H2	N

Note:

H: Company Code

H2: Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



				Note:	
1	25	150	60 90sec;	1.Preheating:25~150	, Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5	, Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices